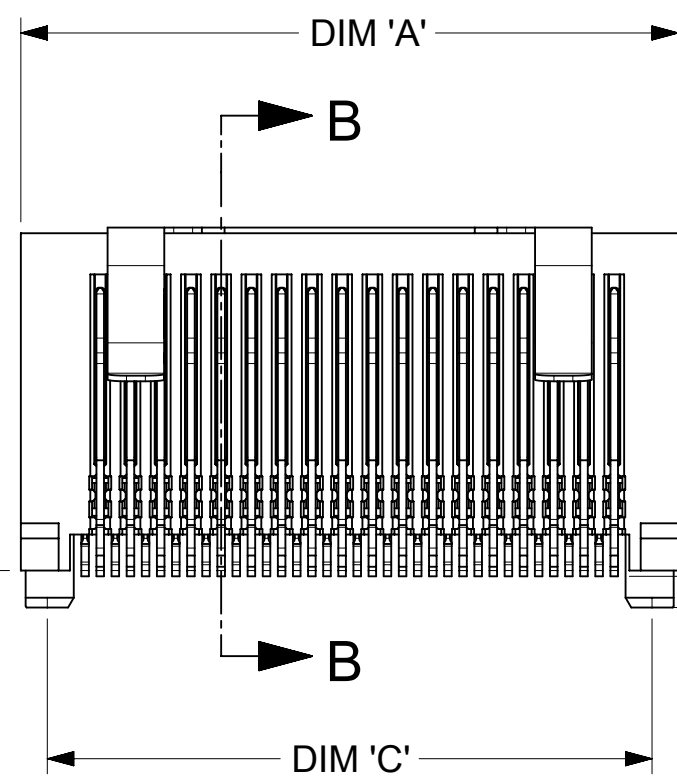
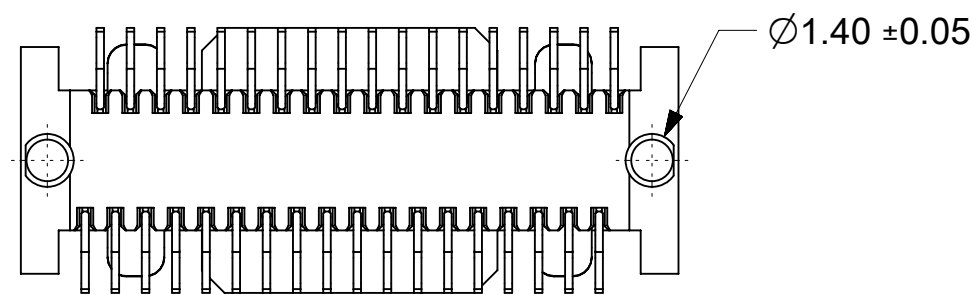


36 CIRCUIT ASSEMBLY SHOWN

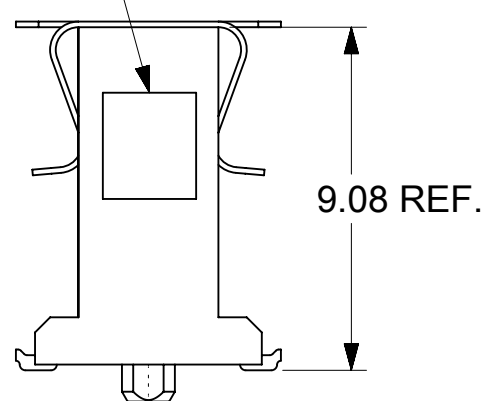


SEE NOTE 3

0.83

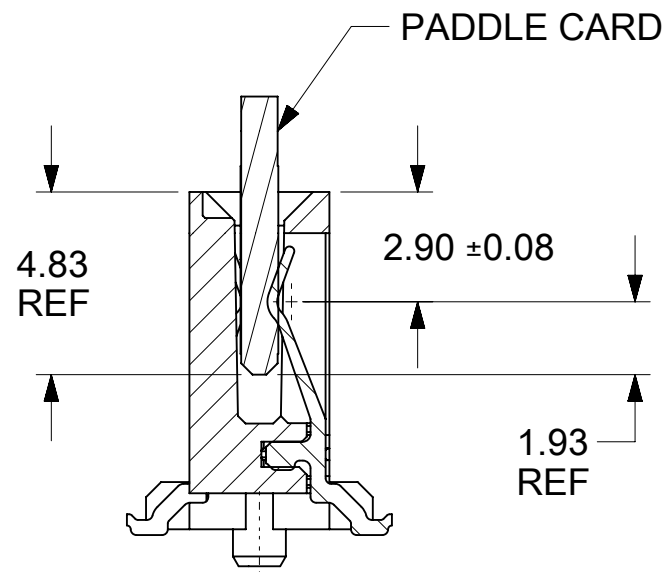


DATE CODE LOCATION
SEE NOTE 4

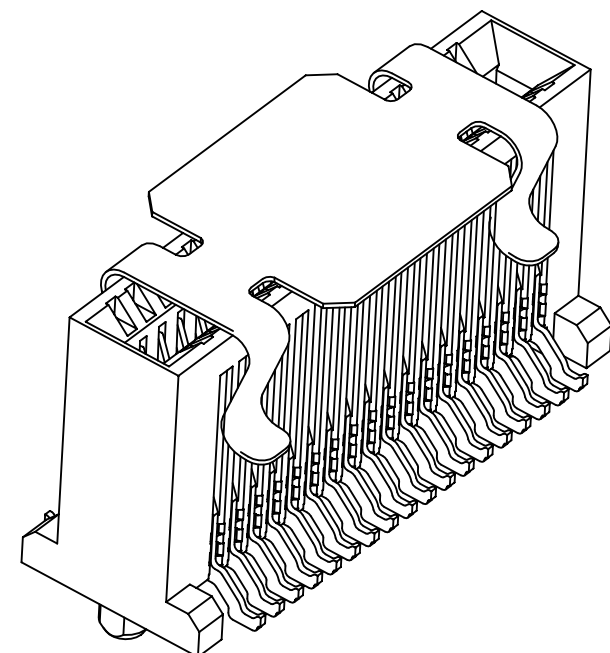


NOTES:

1. MATERIAL:
HOUSING - HIGH TEMPERATURE THERMOPLASTIC GLASS FILLED, UL 94V-0, BLACK
TERMINALS - COPPER ALLOY
2. TERMINAL PLATING:
OPTION 1
CONTACT AREA: 0.38µm HARD GOLD OVER 2.54µm NICKEL
SOLDER AREA: 2.54-5.09µm TIN OVER 1.27µm NICKEL
OPTION 2
CONTACT AREA: 0.76µm HARD GOLD OVER 2.54µm NICKEL
SOLDER AREA: 2.54-5.09µm TIN OVER 1.27µm NICKEL
3. TERMINAL SOLDER FEET TO BE COPLANAR WITHIN 0.10/.004 MEASURED FROM FRONT HOUSING STANDOFF (DATUM E)
4. DATE CODE: 4 DIGIT (3 DIGIT DAY, 1 DIGIT YEAR)
5. CIRCUIT IDENTIFIER: SEE APPROPRIATE INDUSTRY SPECIFICATION FOR LOCATION OF PIN 1
6. MATES WITH:
A. INTERNAL CABLE SERIES:
79575/74563/79576/74573/79536/74562/74569/74586
B. PADDLE CARD PCB: DO NOT BOTTOM OUT PCB IN THE CONNECTOR. SEE SECTION Z-Z.
USE WITH APPROPRIATE INTERNAL SHELL FROM SD-76010-002
7. LITTLE ROCK PACKAGING PER PK-75577-001
CHENGDU PACKAGING PER PK-75577-002
8. CONFORMS TO PRODUCT SPECIFICATION PS-75783-001
9. CONFORMS TO APPLICATION SPECIFICATION AS-75783-001



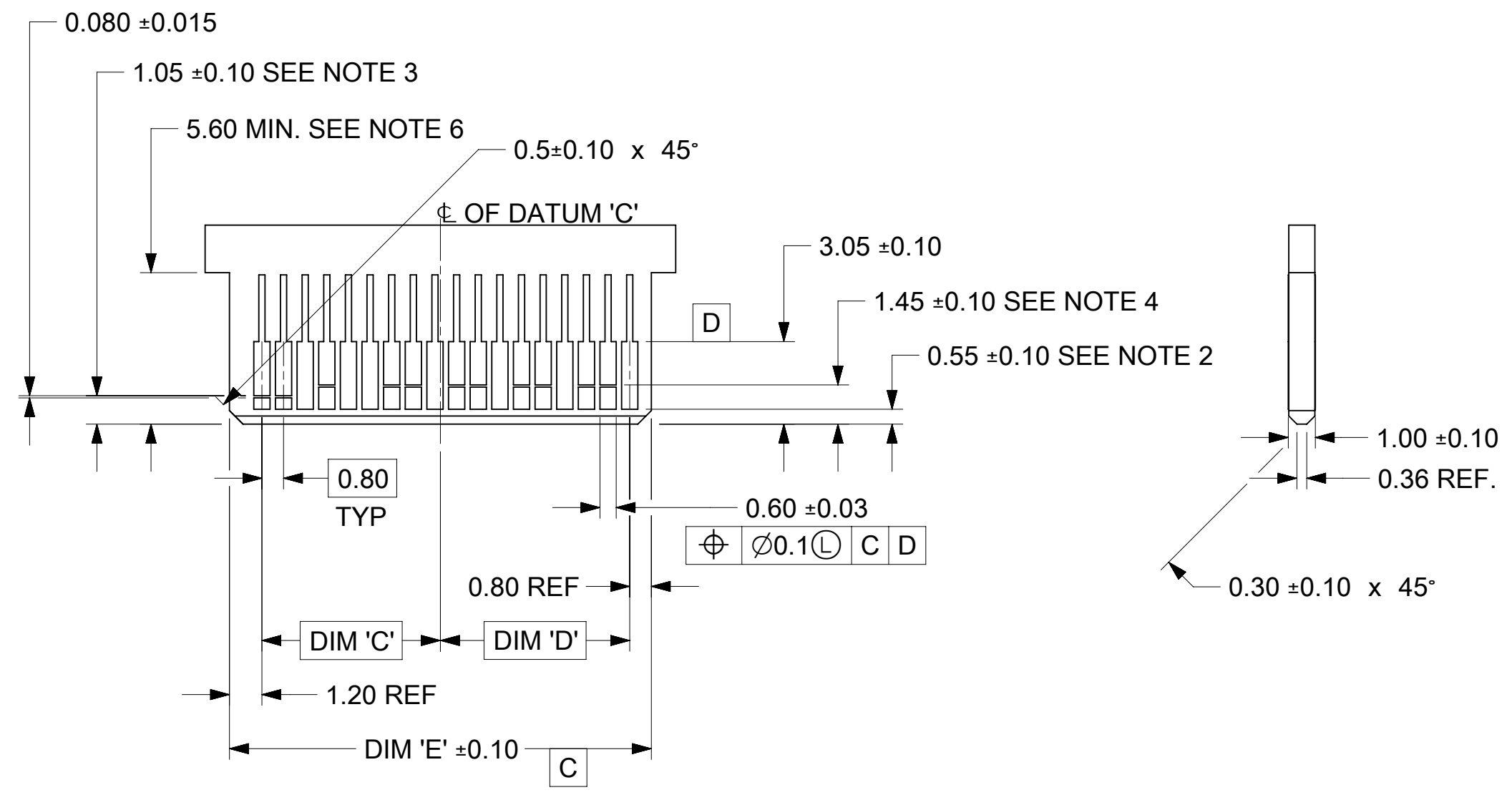
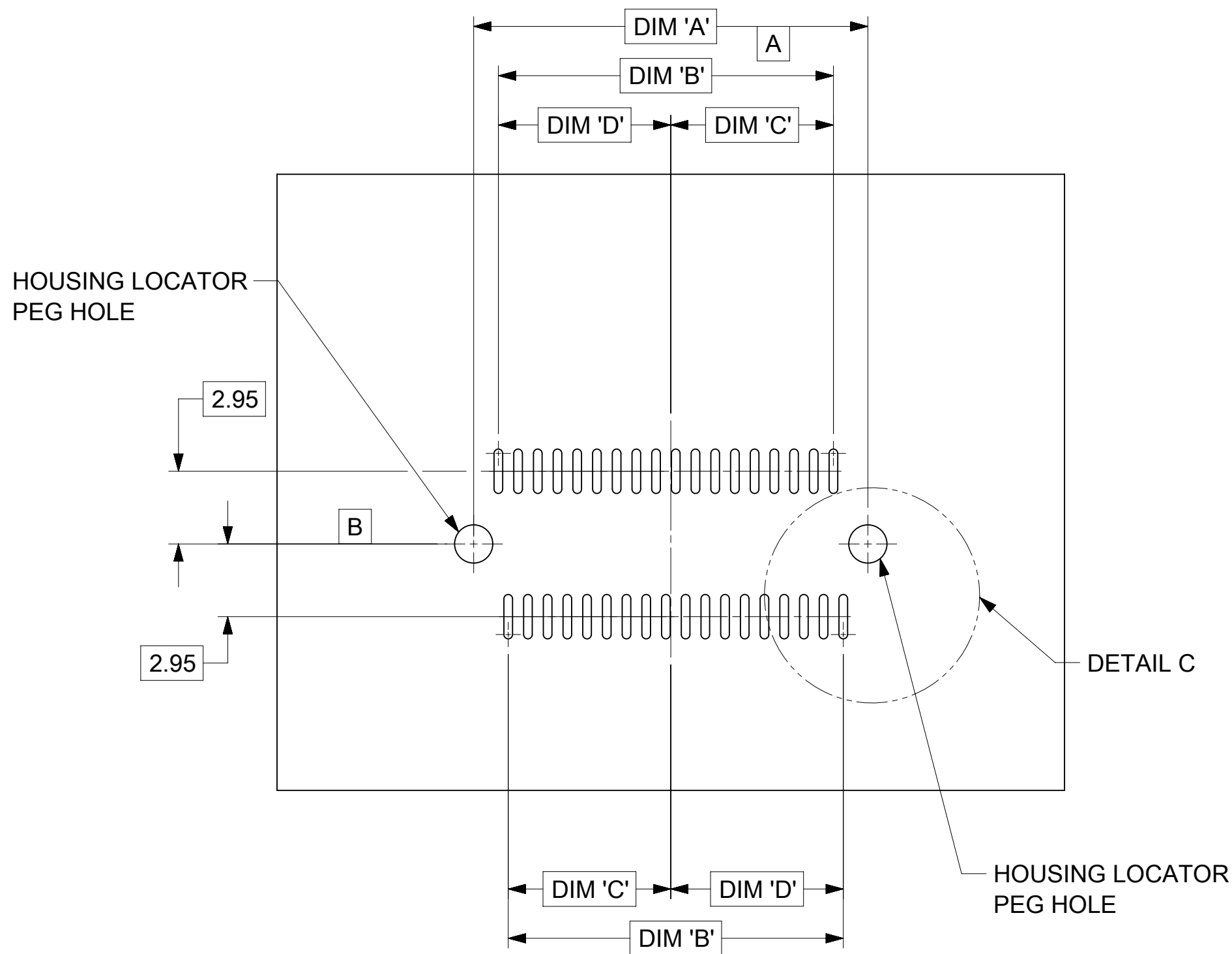
SECTION B-B



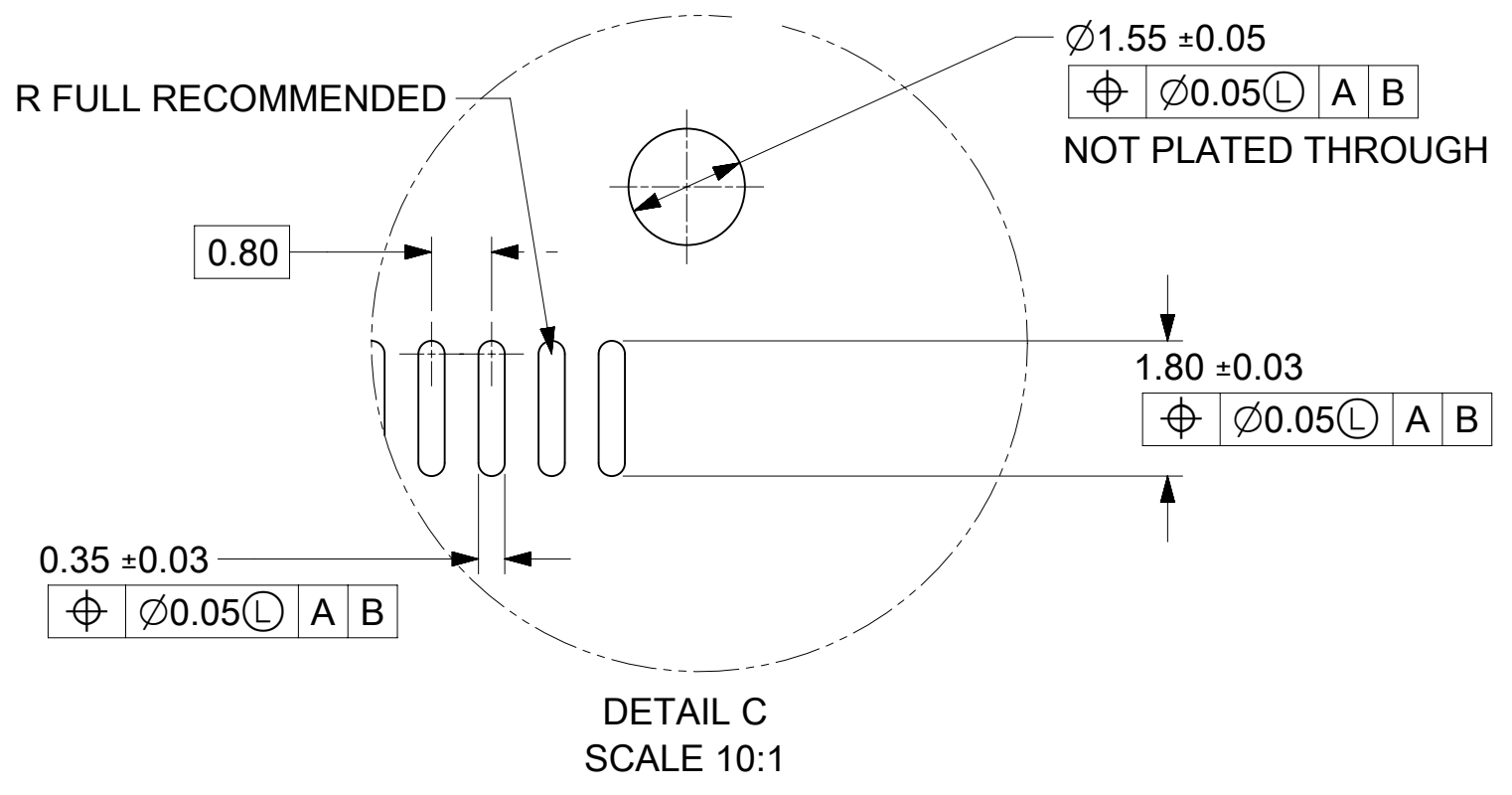
CIRCUIT SIZE	MAT'L NUMBER	PLATING OPTION	DIM 'A'	DIM 'B'	DIM 'C'
36	75577-1002	OPTION 1	17.40	15.80	16.00
68	75577-1004	OPTION 1	30.20	28.60	28.80

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

DIMENSION UNITS mm	SCALE 5:1	CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#511698.		molex		
GENERAL TOLERANCES (UNLESS SPECIFIED)		EC NO: 742551				
4 PLACES	±	MM	INCH	DRWN: SANTHN	2023/03/30	PRODUCT CUSTOMER DRAWING
3 PLACES	±			CHK'D: GGA	2023/05/12	
2 PLACES	± 0.13			APPR: GGA	2023/05/12	DOCUMENT NUMBER SD-75577-002
1 PLACE	± 0.25			INITIAL REVISION:		
0 PLACES	±			DRWN: JLSWENSON	06/07/07	DOC PART 001
ANGULAR TOL	± 0.5 °			APPR: MBANAKIS	06/07/07	REVISION E1
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIRD ANGLE PROJECTION	DRAWING	SERIES	MATERIAL NUMBER	CUSTOMER
			C-SIZE	75577	SEE TABLE	GENERAL MARKET
						SHEET NUMBER 1 OF 2



36 CIRCUIT SHOWN
PATTERN FOR REPRESENTATION ONLY



- NOTES:
1. FOR APPROPRIATE SHELL FOOT PRINT AND KEEP OUT AREAS, SEE SD-76010-002
 2. PAD CONFIGURATION FOR FIRST MATE
 3. PAD CONFIGURATION FOR SECOND MATE
 4. PAD CONFIGURATION FOR THIRD MATE (HIGH SPEED SIGNALS)
 5. FOR PIN ASSIGNMENTS AND MATING SEQUENCE (1ST, 2ND, 3RD), SEE APPLICABLE SPECIFICATION
 6. MINIMUM STEP REQUIRED IF PCB MADE WIDER THAN CARD TONGUE
 7. THESE ARE GENERIC DETAILS THAT DESCRIBES THE CONFIGURATION OF VARIOUS PCB DESIGN ELEMENTS. THE CUSTOMER MUST DETERMINE WHERE AND WHEN TO USE EACH ELEMENT TO ACCOMODATE THEIR SPECIFIC APPLICATION.
 8. CHAMFER ROUGHNESS NOT TO EXCEED 3.17µM.
 9. EDGE CARD CHAMFER NOT TO GO THROUGH GOLD PAD.

CIRCUIT SIZE	DIMENSIONS				
	DIM 'A'	DIM 'B'	DIM 'C'	DIM 'D'	DIM 'E'
26	12.00	9.60	4.60	5.00	11.60
36	16.00	13.60	6.60	7.00	15.60
50	21.60	19.20	9.40	9.80	21.20
68	28.80	26.40	13.00	13.40	28.40

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DIMENSION UNITS	SCALE	CURRENT REV DESC: REMOVED OBSOLETE PART NUMBERS AS PER PCN#511698.			
mm	5:1	molex SALES DRAWING IPASS VERTICAL CONNECTOR .8 MM PITCH I/O PRODUCT CUSTOMER DRAWING			
GENERAL TOLERANCES (UNLESS SPECIFIED)					
4 PLACES	±	MM	INCH	EC NO: 742551	2023/03/30
3 PLACES	±			DRWN: SANTHN	2023/05/12
2 PLACES	± 0.13			CHK'D: GGA	2023/05/12
1 PLACE	± 0.25			APPR: GGA	2023/05/12
0 PLACES	±			INITIAL REVISION:	
ANGULAR TOL ± 0.5°		THIRD ANGLE PROJECTION		DRWN: JLSWENSON	06/07/07
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DRAWING		APPR: MBANAKIS	06/07/07
		C-SIZE	SERIES	DOCUMENT NUMBER	
			75577	SD-75577-002	
		MATERIAL NUMBER		CUSTOMER	SHEET NUMBER
		SEE TABLE		GENERAL MARKET	2 OF 2